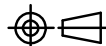
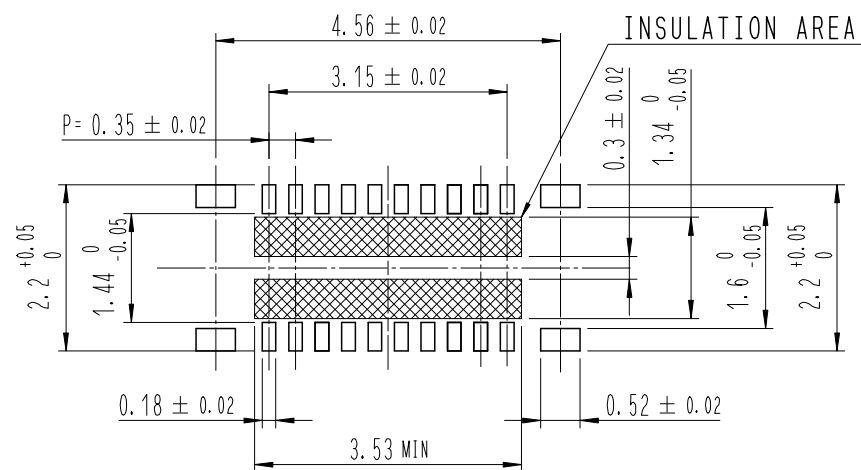
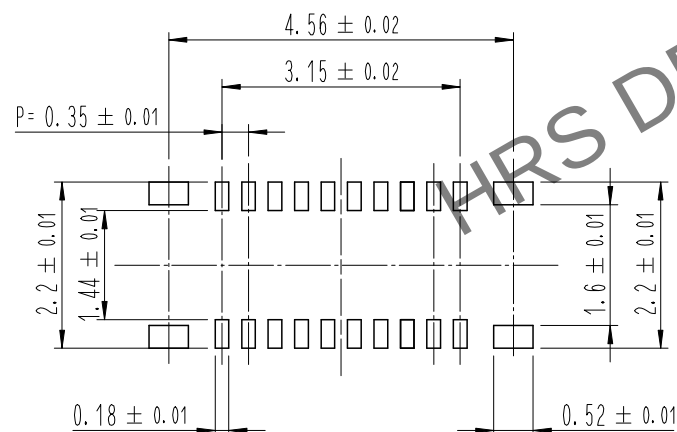


4	PS	CLEAR (EMBOSSED CARRIER TAPE)					
3	COPPER ALLOY	3	7	PS	CLEAR (REINFORCEMENT COLLAR)		
2	COPPER ALLOY	2	6	PS	BLACK (PLASTIC REEL)		
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)		
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS		
REMARKS			DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
			S. H. JUNG 17. 05. 08	S. H. JUNG 17. 05. 08	H. W. JO 17. 05. 08	T. S. KANG 17. 05. 08	17. 05. 08
CODE NO. (OLD)		DRAWING NO.	PART NO. BM23FR0. 6-20DS-0. 35V(895)				
	SCALE 10:1	EDC3-631851					
	UNITS mm	 HIROSE KOREA CO., LTD.	CODE NO	CL 6644-0010-8-895		1/3	

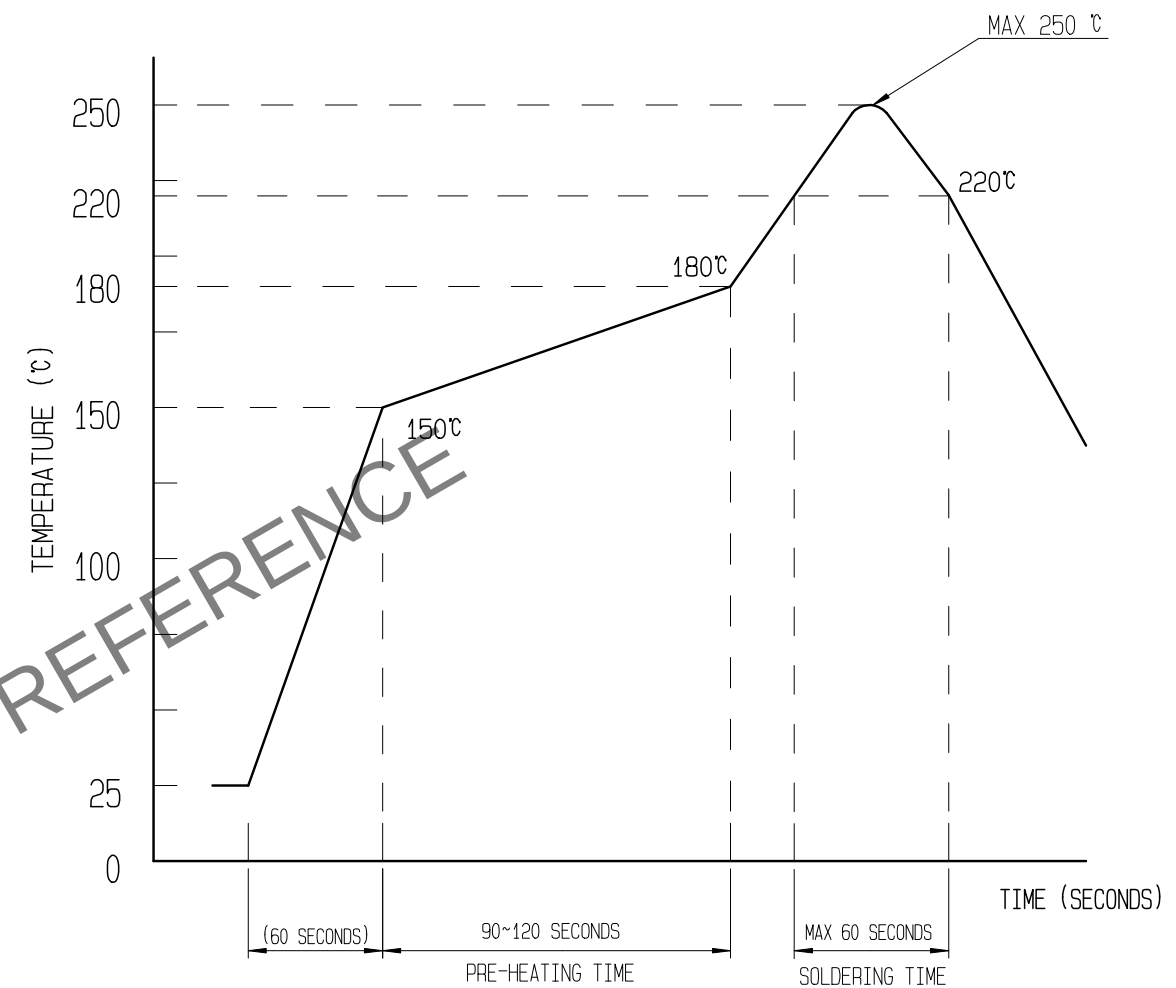
6 RECOMMENDED PCB LAYOUT



RECOMMENDED METAL MASK DIMENSIONS
MATAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N2 REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220°C: 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE (MIN): 150°C
PRE-HEAT TEMPERATURE (MAX): 180°C
PRE-HEAT TIME: 90~120 SEC.

5. THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
6. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-631851	PART NO.	BM23FR0.6-20DS-0.35V(895)
	SCALE	10:1	CODE NO	CL 6644-0010-8-895
	UNITS	mm		2/3

